# Sleep-Mode™ Two-State, Micropower Operational Amplifier

The MC33102 dual operational amplifier is an innovative design concept employing Sleep–Mode technology. Sleep–Mode amplifiers have two separate states, a sleepmode and an awakemode. In sleepmode, the amplifier is active and waiting for an input signal. When a signal is applied causing the amplifier to source or sink 160  $\mu$ A (typically) to the load, it will automatically switch to the awakemode which offers higher slew rate, gain bandwidth, and drive capability.

- Two States: "Sleepmode" (Micropower) and "Awakemode" (High Performance)
- Switches from Sleepmode to Awakemode in 4.0  $\mu$ s when Output Current Exceeds the Threshold Current (R<sub>L</sub> = 600  $\Omega$ )
- Independent Sleepmode Function for Each Op Amp
- Standard Pinouts No Additional Pins or Components Required
- Sleepmode State Can Be Used in the Low Current Idle State as a Fully Functional Micropower Amplifier
- Automatic Return to Sleepmode when Output Current Drops Below Threshold
- No Deadband/Crossover Distortion; as Low as 1.0 Hz in the Awakemode
- Drop-in Replacement for Many Other Dual Op Amps
- ESD Clamps on Inputs Increase Reliability without Affecting Device Operation

## TYPICAL SLEEPMODE/AWAKEMODE PERFORMANCE

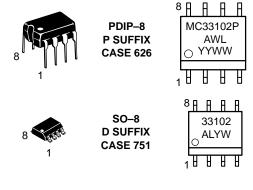
Characteristic	Sleepmode (Typical)	Awakemode (Typical)	Unit
Low Current Drain	45	750	μA
Low Input Offset Voltage	0.15	0.15	mV
High Output Current Capability	0.15	50	mA
Low T.C. of Input Offset Voltage	1.0	1.0	μV/°C
High Gain Bandwidth (@ 20 kHz)	0.33	4.6	MHz
High Slew Rate	0.16	1.7	V/µs
Low Noise (@ 1.0 kHz)	28	9.0	nV/√Hz



# **ON Semiconductor**

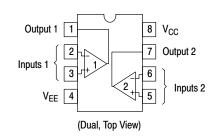
http://onsemi.com

#### MARKING DIAGRAMS



A = Assembly Location WL, L = Wafer Lot YY, Y = Year WW, W = Work Week

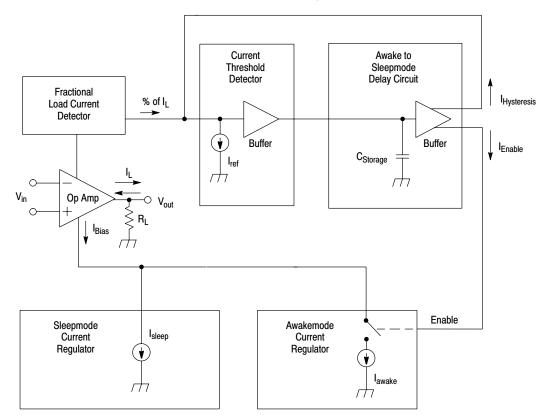
## PIN CONNECTIONS



## ORDERING INFORMATION

Device	Package	Shipping
MC33102D	SO–8	98 Units/Rail
MC33102DR2	SO–8	2500 Tape & Reel
MC33102P	PDIP-8	50 Units/Rail

#### Simplified Block Diagram



#### MAXIMUM RATINGS

Ratings	Symbol	Value	Unit
Supply Voltage (V <sub>CC</sub> to V <sub>EE</sub> )	VS	+36	V
Input Differential Voltage Range Input Voltage Range	V <sub>IDR</sub> V <sub>IR</sub>	Note 1.	V
Output Short Circuit Duration (Note 2.)	t <sub>SC</sub>	Note 2.	sec
Maximum Junction Temperature Storage Temperature	T <sub>J</sub> T <sub>stg</sub>	+150 –65 to +150	°C
Maximum Power Dissipation	P <sub>D</sub>	Note 2.	mW

Either or both input voltages should not exceed V<sub>CC</sub> or V<sub>EE</sub>.
 Power dissipation must be considered to ensure maximum junction temperature (T<sub>J</sub>) is not exceeded (refer to Figure 1).

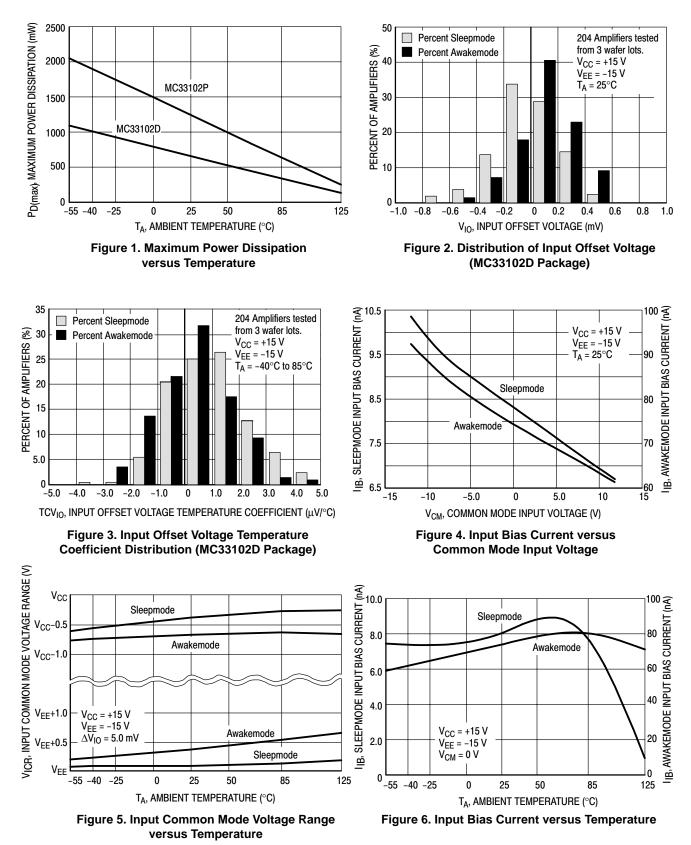
DC ELECTRICAL CHARACTERISTICS	(V <sub>CC</sub> = +15 V, V <sub>EE</sub> = $-15$ V, T <sub>A</sub> = $25^{\circ}$ C, unless otherwise noted.)
-------------------------------	--

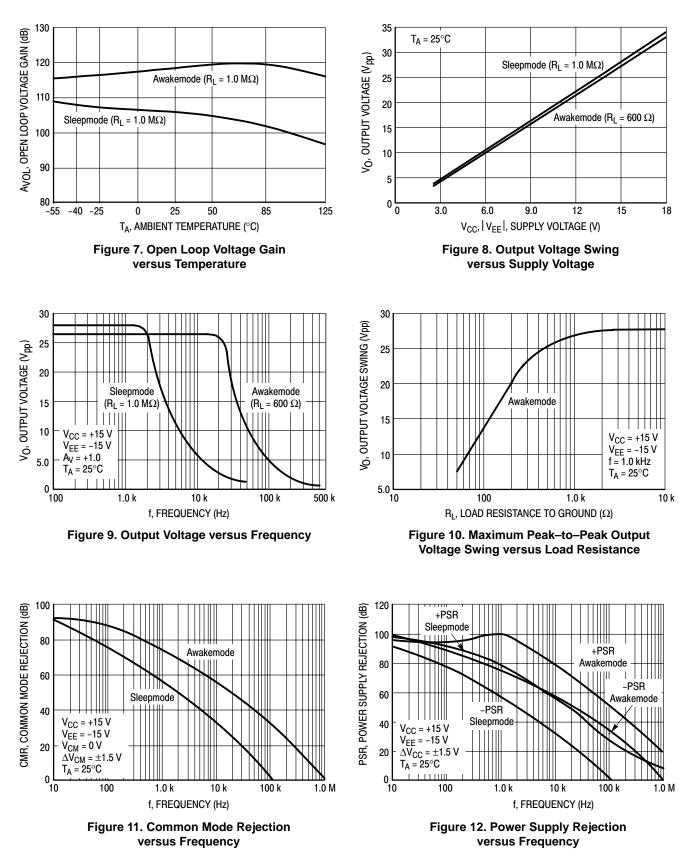
Figure	Symbol	Min	Тур	Max	Unit
2	V <sub>IO</sub>				mV
			0.15 -	2.0 3.0	
			0.15 -	2.0 3.0	
3	$\Delta V_{IO} / \Delta T$				μV/°C
4.0	1	-	1.0	-	
4, 0	IΒ		8.0 -	50 60	nA
			100 -	500 600	
_	lı <sub>lO</sub> l	_	0.5	5.0	nA
			- 5.0 -	50 60	
5	V <sub>ICR</sub>	12	14.9		V
		-13	+14.2	+13	
7	A <sub>VOL</sub>	25	200		kV/V
		15	-	_	
		50 25	700 -		
8, 9, 10					V
	V <sub>O+</sub> V <sub>O-</sub>	+13.5 -	+14.2 -14.2	_ _13.5	v
	V <sub>O+</sub> V <sub>O-</sub>	+12.5 -	+13.6 -13.6	_ _12.5	v
	V <sub>O+</sub> V <sub>O-</sub>	+13.3	+14 -14	_ _13.3	
	V <sub>O+</sub> V <sub>O-</sub>	+1.1	+1.6 -1.6	_ _1.1	
11	CMR	80	90	_	dB
12	PSR	1			dB
	2 2 3 4, 6 - 5 7 8, 9, 10 8, 9, 10	2          V <sub>IO</sub>             3         ΔV <sub>IO</sub> /ΔT           4, 6         I <sub>IB</sub> -         II <sub>IO</sub> 5         V <sub>ICR</sub> 7         A <sub>VOL</sub> 8, 9, 10         V <sub>O+</sub>	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$

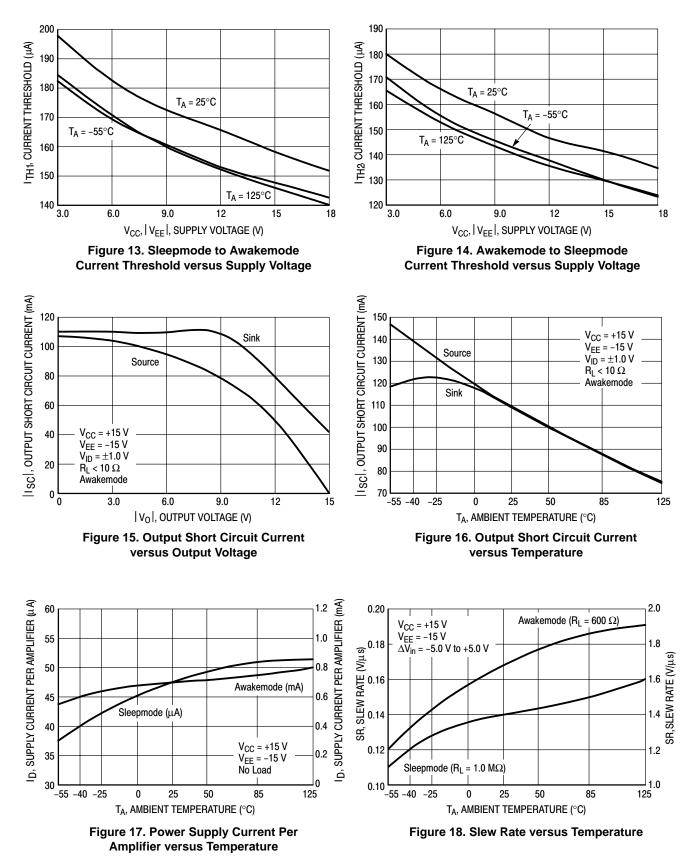
Characteristics	Figure	Symbol	Min	Тур	Max	Unit
Output Transition Current Sleepmode to Awakemode (Source/Sink)	13, 14	I <sub>TH1</sub>				μΑ
$(V_{S} = \pm 15 \text{ V})$			200	160	-	
$(V_{S} = \pm 2.5 V)$			250	200	-	
Awakemode to Sleepmode (Source/Sink)		I <sub>TH2</sub>				
$(V_{S} = \pm 15 V)$			-	142	90	
$(V_{S} = \pm 2.5 V)$			-	180	140	
Output Short Circuit Current (Awakemode) ( $V_{ID} = \pm 1.0 V$ , Output to Ground)	15, 16	I <sub>SC</sub>				mA
Source			50	110	-	
Sink			50	110	-	
Power Supply Current (per Amplifier) ( $A_{CL} = 1$ , $V_O = 0V$ ) Sleepmode ( $V_S = \pm 15 V$ )	17	I <sub>D</sub>				μA
$T_A = +25^{\circ}C$			-	45	65	
$T_{A} = -40^{\circ} \text{ to } +85^{\circ}\text{C}$			_	48	70	
Sleepmode ( $V_S = \pm 2.5 V$ )						
$T_A = +25^{\circ}C$			-	38	65	
$T_A = -40^\circ$ to +85°C			-	42	-	
Awakemode ( $V_S = \pm 15 V$ )						
$T_A = +25^{\circ}C$			-	750	800	
$T_{A} = -40^{\circ} \text{ to } +85^{\circ}\text{C}$			-	800	900	

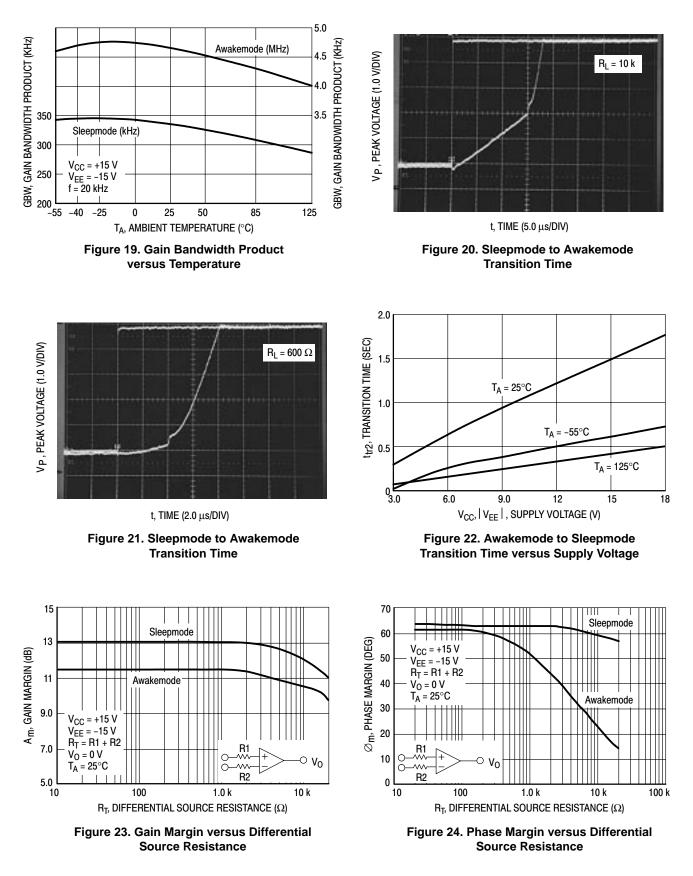
## **DC ELECTRICAL CHARACTERISTICS** ( $V_{CC} = +15 \text{ V}, V_{EE} = -15 \text{ V}, T_A = 25^{\circ}\text{C}$ , unless otherwise noted.)

Characteristics	Figure	Symbol	Min	Тур	Max	Unit
Slew Rate (V <sub>in</sub> = -5.0 V to +5.0 V, C <sub>L</sub> = 50 pF, A <sub>V</sub> = 1.0) Sleepmode (R <sub>L</sub> = 1.0 M $\Omega$ ) Awakemode (R <sub>L</sub> = 600 $\Omega$ )	18	SR	0.10 1.0	0.16 1.7		V/µs
Gain Bandwidth Product Sleepmode (f = 10 kHz) Awakemode (f = 20 kHz)	19	GBW	0.25 3.5	0.33 4.6		MHz
Sleepmode to Awakemode Transition Time $(A_{CL} = 0.1, V_{in} = 0 V \text{ to } +5.0 V)$ $R_L = 600 \Omega$ $R_I = 10 \text{ k}\Omega$	20, 21	t <sub>tr1</sub>		4.0 15		μs
Awakemode to Sleepmode Transition Time	22	t <sub>tr2</sub>	_	1.5	_	sec
Unity Gain Frequency (Open Loop) Sleepmode ( $R_L = 100 \text{ k}\Omega$ , $C_L = 0 \text{ pF}$ ) Awakemode ( $R_L = 600 \Omega$ , $C_L = 0 \text{ pF}$ )		fU		200 2500		kHz
Gain Margin Sleepmode ( $R_L = 100 \text{ k}\Omega$ , $C_L = 0 \text{ pF}$ ) Awakemode ( $R_L = 600 \Omega$ , $C_L = 0 \text{ pF}$ )	23, 25	A <sub>M</sub>		13 12		dB
Phase Margin Sleepmode ( $R_L = 100 \text{ k}\Omega$ , $C_L = 0 \text{ pF}$ ) Awakemode ( $R_L = 600 \Omega$ , $C_L = 0 \text{ pF}$ )	24, 26	Ø <sub>M</sub>		60 60		Degree s
Channel Separation (f = 100 Hz to 20 kHz) Sleepmode and Awakemode	29	CS	-	120	_	dB
Power Bandwidth (Awakemode) $(V_O = 10 V_{pp}, R_L = 100 k\Omega, THD \le 1\%)$		BW <sub>P</sub>	_	20	_	kHz
Total Harmonic Distortion ( $V_O = 2.0 V_{pp}$ , $A_V = 1.0$ ) Awakemode ( $R_L = 600 \Omega$ ) f = 1.0  kHz f = 10  kHz f = 20  kHz	30	THD	_ _ _	0.005 0.016 0.031		%
DC Output Impedance (V_O = 0 V, A_V = 10, I_Q = 10 $\mu A$ ) Sleepmode Awakemode	31	R <sub>O</sub>		1.0 k 96	_	Ω
Differential Input Resistance (V <sub>CM</sub> = 0 V) Sleepmode Awakemode		R <sub>in</sub>		1.3 0.17		MΩ
Differential Input Capacitance (V <sub>CM</sub> = 0 V) Sleepmode Awakemode		C <sub>in</sub>		0.4 4.0		pF
Equivalent Input Noise Voltage (f = 1.0 kHz, $R_S = 100 \Omega$ ) Sleepmode Awakemode	32	e <sub>n</sub>		28 9.0		nV/√Hz
Equivalent Input Noise Current (f = 1.0 kHz) Sleepmode Awakemode	33	i <sub>n</sub>		0.01 0.05		pA/√Hz









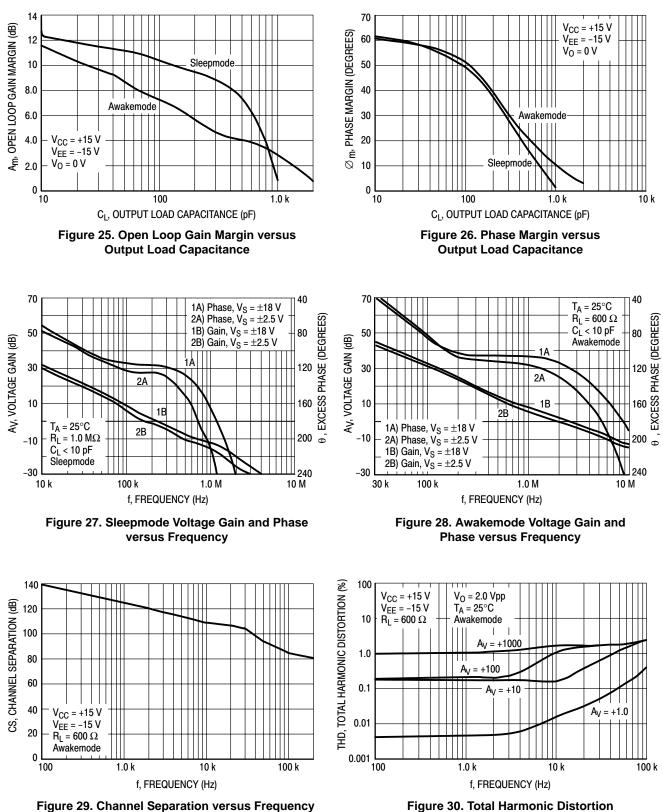
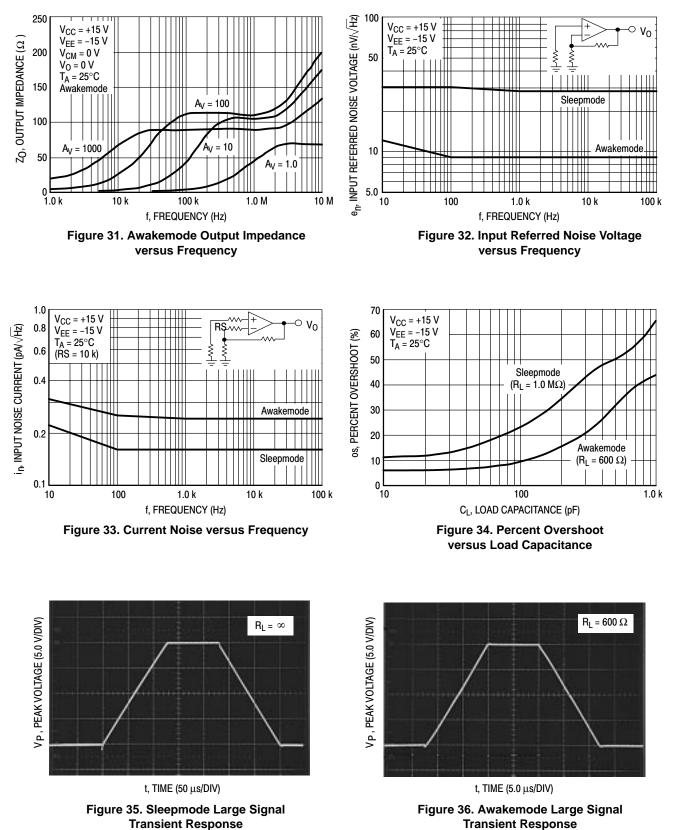


Figure 30. Total Harmonic Distortion versus Frequency



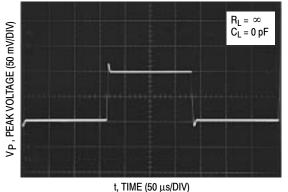


Figure 37. Sleepmode Small Signal Transient Response

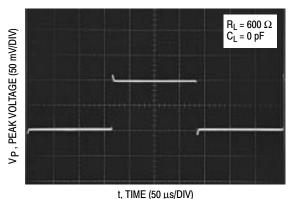


Figure 38. Awakemode Small Signal Transient Response

#### **CIRCUIT INFORMATION**

The MC33102 was designed primarily for applications where high performance (which requires higher current drain) is required only part of the time. The two–state feature of this op amp enables it to conserve power during idle times, yet be powered up and ready for an input signal. Possible applications include laptop computers, automotive, cordless phones, baby monitors, and battery operated test equipment. Although most applications will require low power consumption, this device can be used in any application where better efficiency and higher performance is needed.

The Sleep–Mode<sup>TM</sup> amplifier has two states; a sleepmode and an awakemode. In the sleepmode state, the amplifier is active and functions as a typical micropower op amp. When a signal is applied to the amplifier causing it to source or sink sufficient current (see Figure 13), the amplifier will automatically switch to the awakemode. See Figures 20 and 21 for transition times with 600  $\Omega$  and 10 k $\Omega$  loads. The awakemode uses higher drain current to provide a high slew rate, gain bandwidth, and output current capability. In the awakemode, this amplifier can drive 27 Vpp into a 600  $\Omega$  load with V<sub>S</sub> = ±15 V.

An internal delay circuit is used to prevent the amplifier from returning to the sleepmode at every zero crossing. This delay circuit also eliminates the crossover distortion commonly found in micropower amplifiers. This amplifier can process frequencies as low as 1.0 Hz without the amplifier returning to sleepmode, depending on the load.

The first stage PNP differential amplifier provides low noise performance in both the sleep and awake modes, and an all NPN output stage provides symmetrical source and sink AC frequency response.

#### **APPLICATIONS INFORMATION**

The MC33102 will begin to function at power supply voltages as low as  $V_S = \pm 1.0$  V at room temperature. (At this voltage, the output voltage swing will be limited to a few hundred millivolts.) The input voltages must range between  $V_{CC}$  and  $V_{EE}$  supply voltages as shown in the maximum rating table. Specifically, **allowing the input to go more negative than 0.3 V below V**<sub>EE</sub> **may cause product damage.** Also, exceeding the input common mode voltage range on either input may cause phase reversal, even if the inputs are between  $V_{CC}$  and  $V_{EE}$ .

When power is initially applied, the part may start to operate in the awakemode. This is because of the currents generated due to charging of internal capacitors. When this occurs and the sleepmode state is desired, the user will have to wait approximately 1.5 seconds before the device will switch back to the sleepmode. To prevent this from occurring, ramp the power supplies from 1.0 V to full supply. Notice that the device is more prone to switch into the awakemode when  $V_{EE}$  is adjusted than with a similar change in  $V_{CC}$ .

The amplifier is designed to switch from sleepmode to awakemode whenever the output current exceeds a preset current threshold (I<sub>TH</sub>) of approximately 160  $\mu$ A. As a result, the output switching threshold voltage (V<sub>ST</sub>) is controlled by the output loading resistance (R<sub>L</sub>). This loading can be a load resistor, feedback resistors, or both. Then:

## $V_{ST} = (160 \ \mu A) \times R_L$

Large valued load resistors require a large output voltage to switch, but reduce unwanted transitions to the awakemode. For instance, in cases where the amplifier is connected with a large closed loop gain ( $A_{CL}$ ), the input offset voltage ( $V_{IO}$ ) is multiplied by the gain at the output and could produce an output voltage exceeding  $V_{ST}$  with no input signal applied.

Small values of  $R_L$  allow rapid transition to the awakemode because most of the transition time is consumed slewing in the sleepmode until  $V_{ST}$  is reached (see Figures 20, 21). The output switching threshold voltage  $V_{ST}$  is higher for larger values of  $R_L$ , requiring the amplifier to slew longer in the slower sleepmode state before switching to the awakemode.

The transition time  $(t_{tr1})$  required to switch from sleep to awake mode is:

$$t_{tr1} = t_D = I_{TH}(R_L/SR_{sleepmode})$$

Where:

 $t_D = \text{Amplifier delay} (<1.0 \ \mu\text{s}) \\ I_{TH} = \text{Output threshold current for more transition} \\ (160 \ \mu\text{A}) \\ R_L = \text{Load resistance} \\ SR_{sleepmode} = \text{Sleepmode slew rate} (0.16 \ V/\mu\text{s})$ 

Although typically 160  $\mu$ A, I<sub>TH</sub> varies with supply voltage and temperature. In general, any current loading on the output which causes a current greater than I<sub>TH</sub> to flow will switch the amplifier into the awakemode. This includes transition currents such as those generated by charging load capacitances. In fact, the maximum capacitance that can be driven while attempting to remain in the sleepmode is approximately 1000 pF.

$$C_{L(max)} = I_{TH}/SR_{sleepmode}$$
  
= 160 µA/(0.16 V/µs)  
= 1000 pF

Any electrical noise seen at the output of the MC33102 may also cause the device to transition to the awakemode. To

minimize this problem, a resistor may be added in series with the output of the device (inserted as close to the device as possible) to isolate the op amp from both parasitic and load capacitance.

The awakemode to sleepmode transition time is controlled by an internal delay circuit, which is necessary to prevent the amplifier from going to sleep during every zero crossing. This time is a function of supply voltage and temperature as shown in Figure 22.

Gain bandwidth product (GBW) in both modes is an important system design consideration when using a sleepmode amplifier. The amplifier has been designed to obtain the maximum GBW in both modes. "Smooth" AC transitions between modes with no noticeable change in the amplitude of the output voltage waveform will occur as long as the closed loop gains ( $A_{CL}$ ) in both modes are substantially equal at the frequency of operation. For smooth AC transitions:

## (A<sub>CLsleepmode</sub>) (BW) < GBW<sub>sleepmode</sub>

Where:

A<sub>CLsleepmode</sub> = Closed loop gain in the sleepmode BW = The required system bandwidth or operating frequency

#### **TESTING INFORMATION**

To determine if the MC33102 is in the awakemode or the sleepmode, the power supply currents ( $I_D$ + and  $I_D$ -) must be measured. When the magnitude of **either** power supply current exceeds 400  $\mu$ A, the device is in the awakemode. When the magnitudes of both supply currents are less than 400  $\mu$ A, the device is in the sleepmode. Since the total supply current is typically ten times higher in the awakemode than the sleepmode, the two states are easily distinguishable.

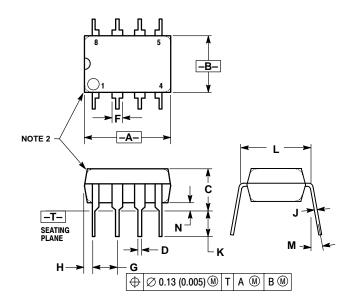
The measured value of  $I_D$ + equals the  $I_D$  of both devices (for a dual op amp) plus the output source current of device A and the output source current of device B. Similarly, the measured value of  $I_D$ - is equal to the  $I_D$ - of both devices plus the output sink current of each device.  $I_{out}$  is the sum of the currents caused by both the feedback loop and load resistance. The total  $I_{out}$  needs to be subtracted from the measured  $I_D$  to obtain the correct  $I_D$  of the dual op amp.

An accurate way to measure the awakemode  $I_{out}$  current on automatic test equipment is to remove the  $I_{out}$  current on both Channel A and B. Then measure the  $I_D$  values before the device goes back to the sleepmode state. The transition will take typically 1.5 seconds with ±15 V power supplies.

The large signal sleepmode testing in the characterization was accomplished with a 1.0 M $\Omega$  load resistor which ensured the device would remain in sleepmode despite large voltage swings.

#### PACKAGE DIMENSIONS

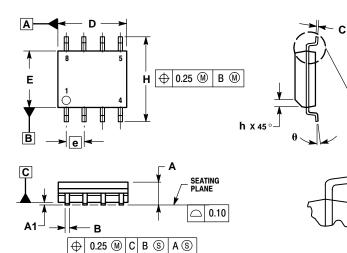
PDIP-8 **P SUFFIX** CASE 626-05 ISSUE K



NOTES: 1. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL. 2. PACKAGE CONTOUR OPTIONAL (ROUND OR SQUARE CONTERS). 3. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.40	10.16	0.370	0.400
В	6.10	6.60	0.240	0.260
C	3.94	4.45	0.155	0.175
D	0.38	0.51	0.015	0.020
F	1.02	1.78	0.040	0.070
G	2.54	BSC	0.100 BSC	
Н	0.76	1.27	0.030	0.050
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62	7.62 BSC		BSC
М		10°		10°
N	0.76	1.01	0.030	0.040

SO-8 **D SUFFIX** CASE 751-06 ISSUE T



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. DIMENSIONS ARE IN MILLIMETER.
3. DIMENSION D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. SHALL BE 0.127 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION. CONDITION.

	MILLIMETERS		
DIM	MIN MAX		
Α	1.35	1.75	
A1	0.10	0.25	
В	0.35	0.49	
C	0.19	0.25	
D	4.80	5.00	
Е	3.80	4.00	
е	1.27	BSC	
Н	5.80	6.20	
h	0.25	0.50	
L	0.40	1.25	
θ	0 °	7 °	

# <u>Notes</u>

#### SLEEPMODE is a trademark of Semiconductor Components Industries, LLC.

**ON Semiconductor** and without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights of thers. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable altorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

#### PUBLICATION ORDERING INFORMATION

#### NORTH AMERICA Literature Fulfillment:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: ONlit@hibbertco.com Fax Response Line: 303–675–2167 or 800–344–3810 Toll Free USA/Canada

N. American Technical Support: 800–282–9855 Toll Free USA/Canada

EUROPE: LDC for ON Semiconductor – European Support

- German Phone: (+1) 303–308–7140 (Mon–Fri 2:30pm to 7:00pm CET) Email: ONlit–german@hibbertco.com French Phone: (+1) 303–308–7141 (Mon–Fri 2:00pm to 7:00pm CET)
- French Phone: (+1) 303–308–7141 (Mon–Fri 2:00pm to 7:00pm CET) Email: ONlit-french@hibbertco.com
- English Phone: (+1) 303–308–7142 (Mon–Fri 12:00pm to 5:00pm GMT) Email: ONlit@hibbertco.com

EUROPEAN TOLL-FREE ACCESS\*: 00-800-4422-3781 \*Available from Germany, France, Italy, England, Ireland

#### CENTRAL/SOUTH AMERICA:

Spanish Phone: 303–308–7143 (Mon–Fri 8:00am to 5:00pm MST) Email: ONlit–spanish@hibbertco.com

ASIA/PACIFIC: LDC for ON Semiconductor – Asia Support Phone: 303–675–2121 (Tue–Fri 9:00am to 1:00pm, Hong Kong Time) Toll Free from Hong Kong & Singapore: 001–800–4422–3781 Email: ONlit–asia@hibbertco.com

JAPAN: ON Semiconductor, Japan Customer Focus Center 4–32–1 Nishi–Gotanda, Shinagawa–ku, Tokyo, Japan 141–0031 Phone: 81–3–5740–2745 Email: r14525@onsemi.com

ON Semiconductor Website: http://onsemi.com

For additional information, please contact your local Sales Representative.